

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00101	0.74	0.06068
	Doped silicon	Silicon (Si)	7440-21-3	0.13614	99.26	8.13932
		Subtotal		0.13715	100	8.2
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.45495	100.0	27.2
		Subtotal		0.45495	100	27.2
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02008	0.03	1.20057
	Copper alloy	Iron (Fe)	7439-89-6	0.06694	0.1	4.0019
	Copper alloy	Copper (Cu)	7440-50-8	66.84846	99.87	3,996.69753
		Subtotal		66.93548	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.09675	6.5	125.359
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.16122	16.0	308.576
	Filler	Silica fused	60676-86-0	22.90291	71.0	1,369.306
	Flame retardant	Metal hydroxide		2.09675	6.5	125.359
		Subtotal		32.25763	100	NaN
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00489	5.0	0.29215
	Lead alloy	Silver (Ag)	7440-22-4	0.00244	2.5	0.14607
	Lead alloy	Lead (Pb)	7439-92-1	0.0904	92.5	5.40468
		Subtotal		0.09773	100	5.8429
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11708	100.0	7
		Subtotal		0.11708	100	7
		Total		100.00002	100	NaN

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